APPLICATION DATA SHEET

APPLICATION INFORMATION

REGULAR Application Type:: Subject Matter:: UTILITY CD-ROM or CD-R?:: NONE

Title:: **HEAT-CONDUCTING MULTILAYER**

SUBSTRATE AND POWER MODULE

SUBSTRATE

Attorney Docket Number:: 246940US2

Total Drawing Sheets:: 2

INVENTOR INFORMATION

INVENTOR Applicant Authority Type::

FULL CAPACITY Status::

Yoshiyuki Given Name:: **NAGATOMO** Family Name::

c/o Mitsubishi Materials Corp, Cntrl Rsrch Street of Mailing Address::

Inst, Naka Rsrch Cntr, 1002-14,

Mukaiyama, Naka-cho

Naka-gun City of Mailing Address:: Ibaraki-ken State or Province of Mailing Address:: Country of Mailing Address:: Japan

INVENTOR

Applicant Authority Type:: **FULL CAPACITY** Status::

Takeshi Given Name:: **NEGISHI** Family Name::

c/o Mitsubishi Materials Corp, Cntrl Rsrch Street of Mailing Address::

Inst, 297 Kitabukuro-cho 1-chome,

Omiya-ku

Saitama-shi City of Mailing Address:: State or Province of Mailing Address:: Saitama-ken

Country of Mailing Address:: Japan **Applicant Authority Type::**

INVENTOR

Status::

FULL CAPACITY

Given Name::

Toshiyuki

Family Name::

NAGASE

Street of Mailing Address::

c/o Mitsubishi Materials Corp, Cntrl Rsrch

Inst, Naka Rsrch Cntr, 1002-14,

Mukaiyama, Naka-cho

City of Mailing Address::

Naka-gun

State or Province of Mailing Address::

Ibaraki-ken

Country of Mailing Address::

Japan

CORRESPONDENCE INFORMATION

Correspondence Customer Number::

22850

REPRESENTATIVE INFORMATION

Representative Customer Number::

22850

FOREIGN PRIORITY INFORMATION

Application Number:	Country::	Filing Date::	Priority Claimed::
2002-380401	Japan	12/27/02	YES
2003-397839	Japan	11/27/03	YES

ASSIGNMENT INFORMATION

Assignee Name::

MITSUBISHI MATERIALS

CORPORATION

Street of Mailing Address::

5-1, Otemachi 1-chome

City of Mailing Address::

Chiyoda-ku

State or Province of Mailing Address::

Tokyo

Country of Mailing Address::

Japan